



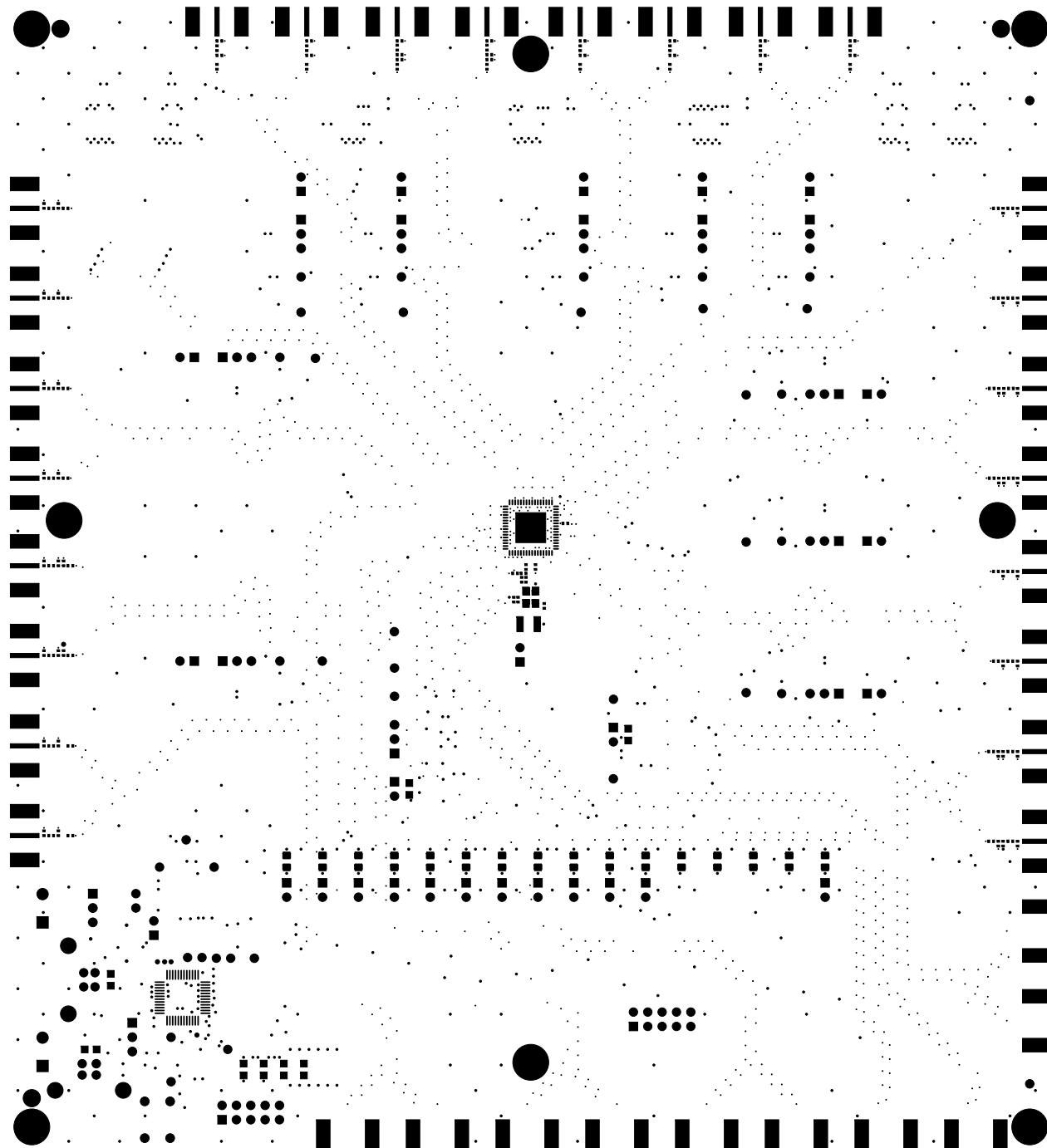




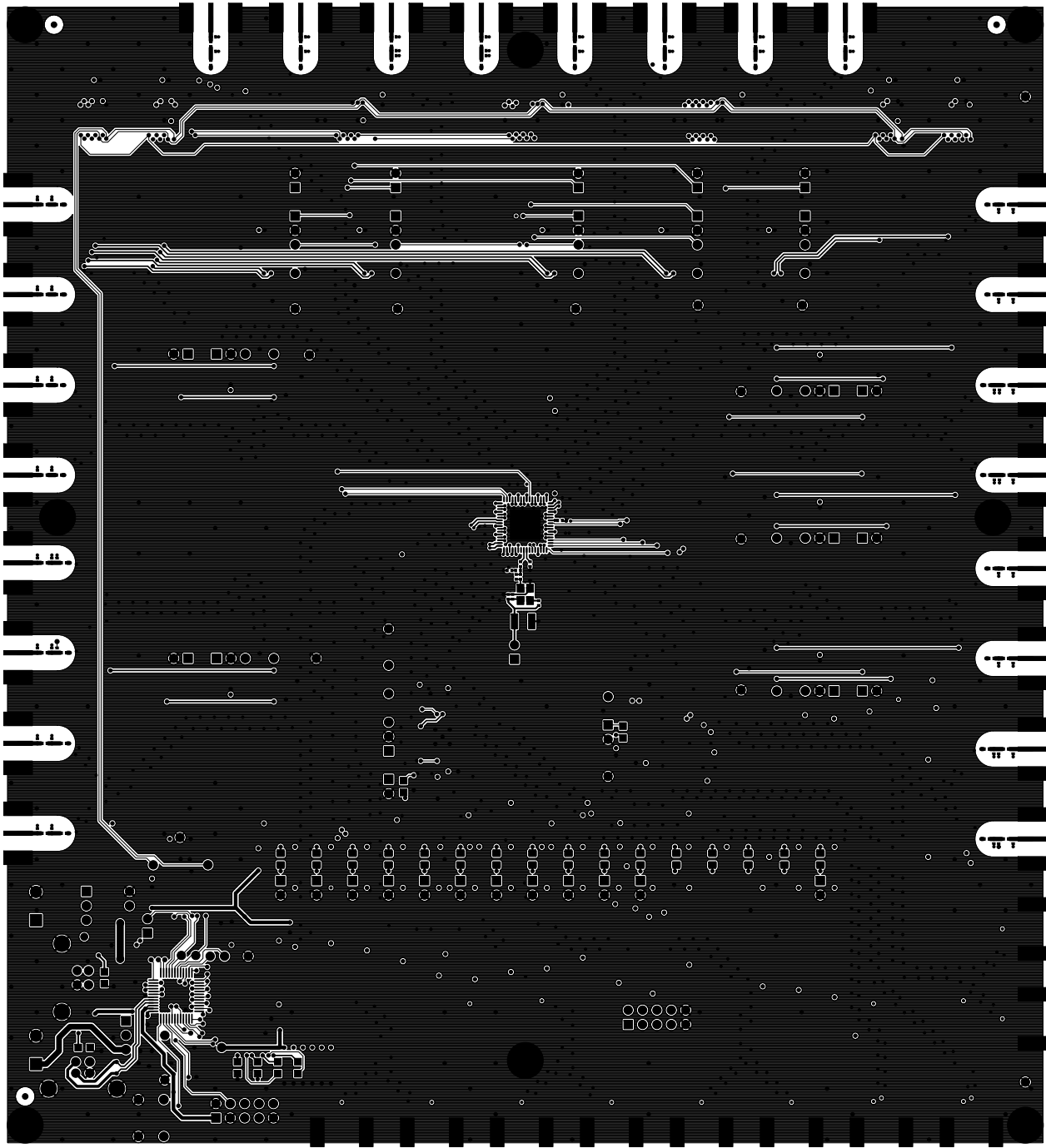




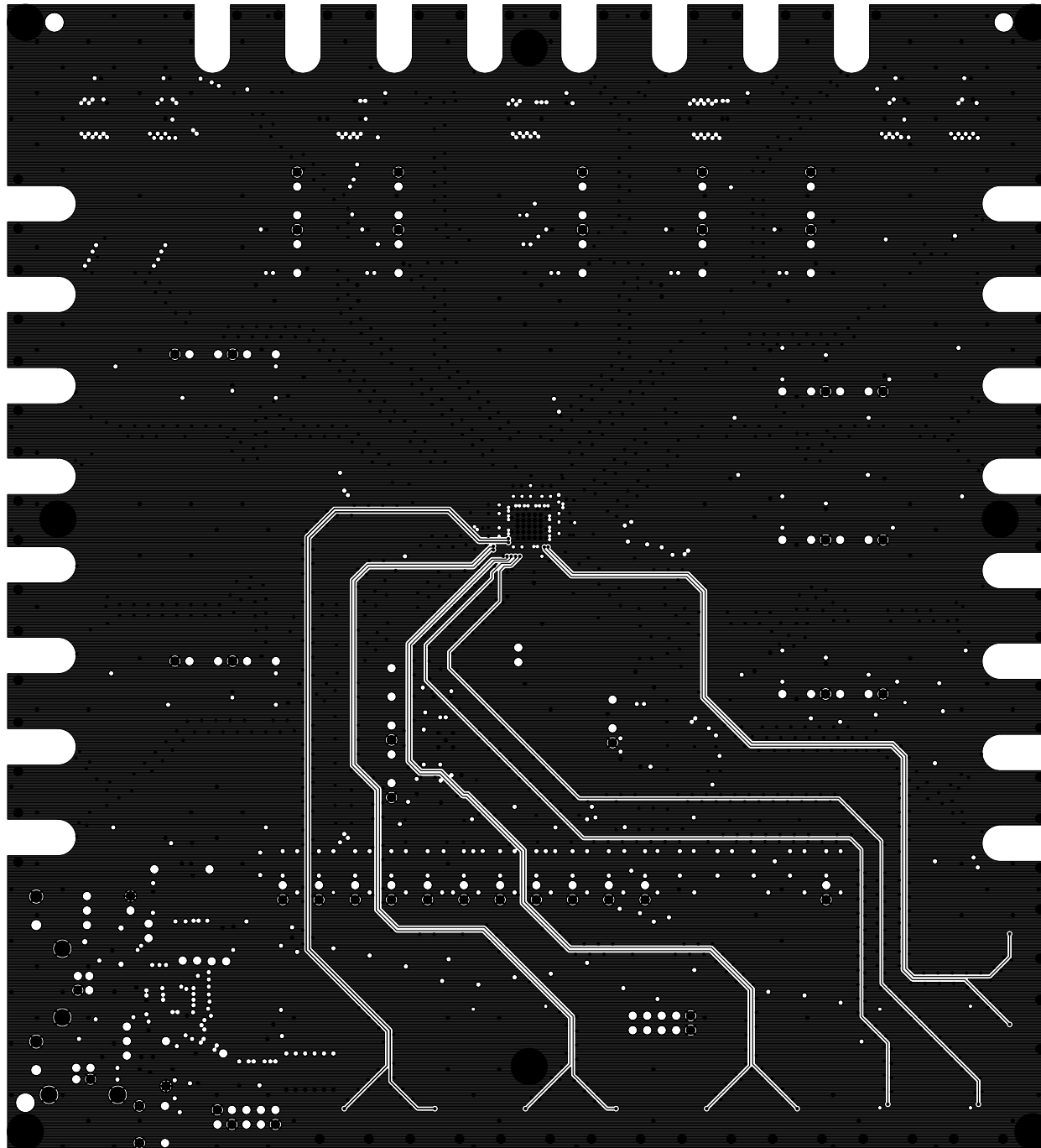
PRIMARY SOLDER MASK



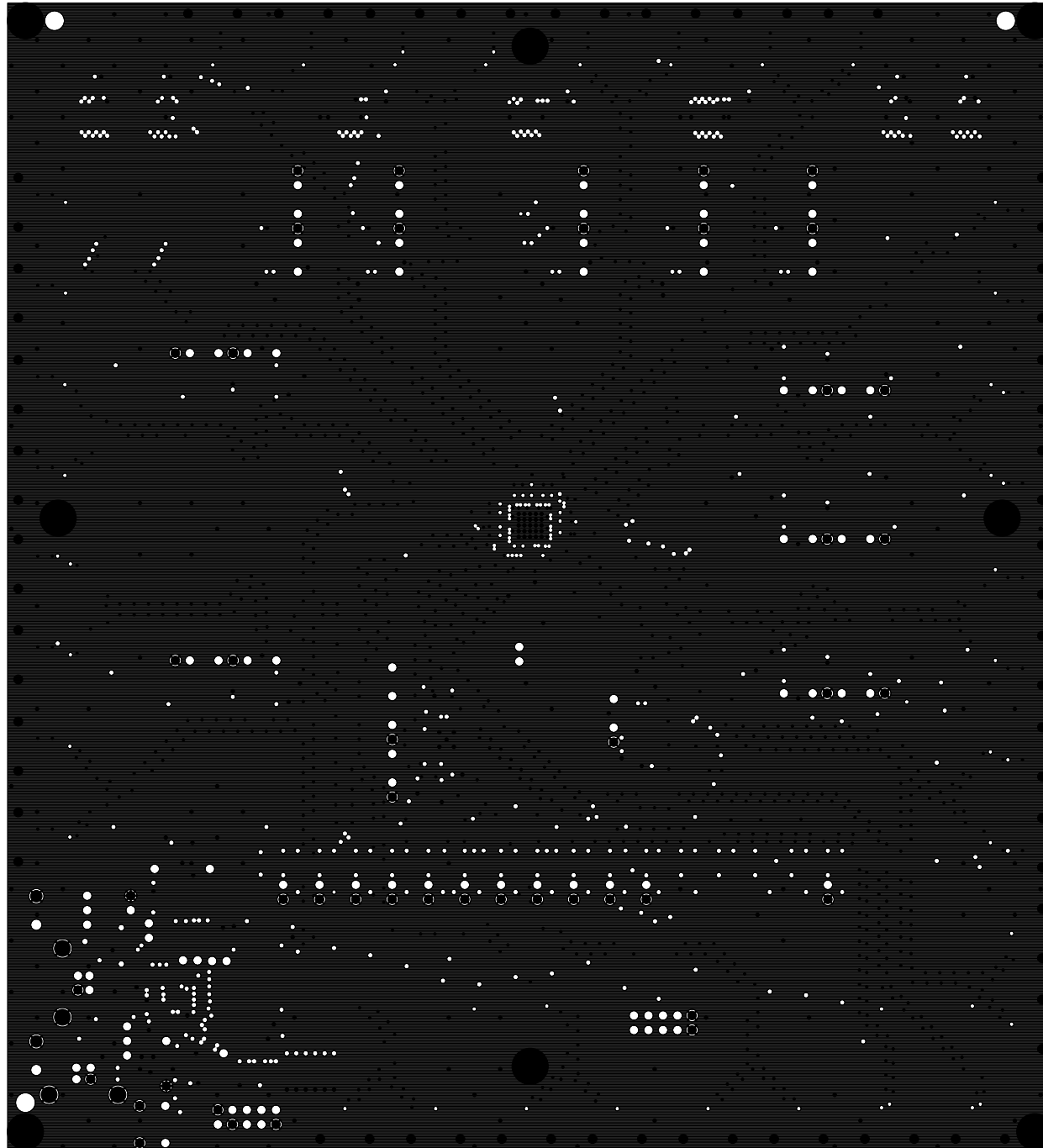
PRIMARY SIDE



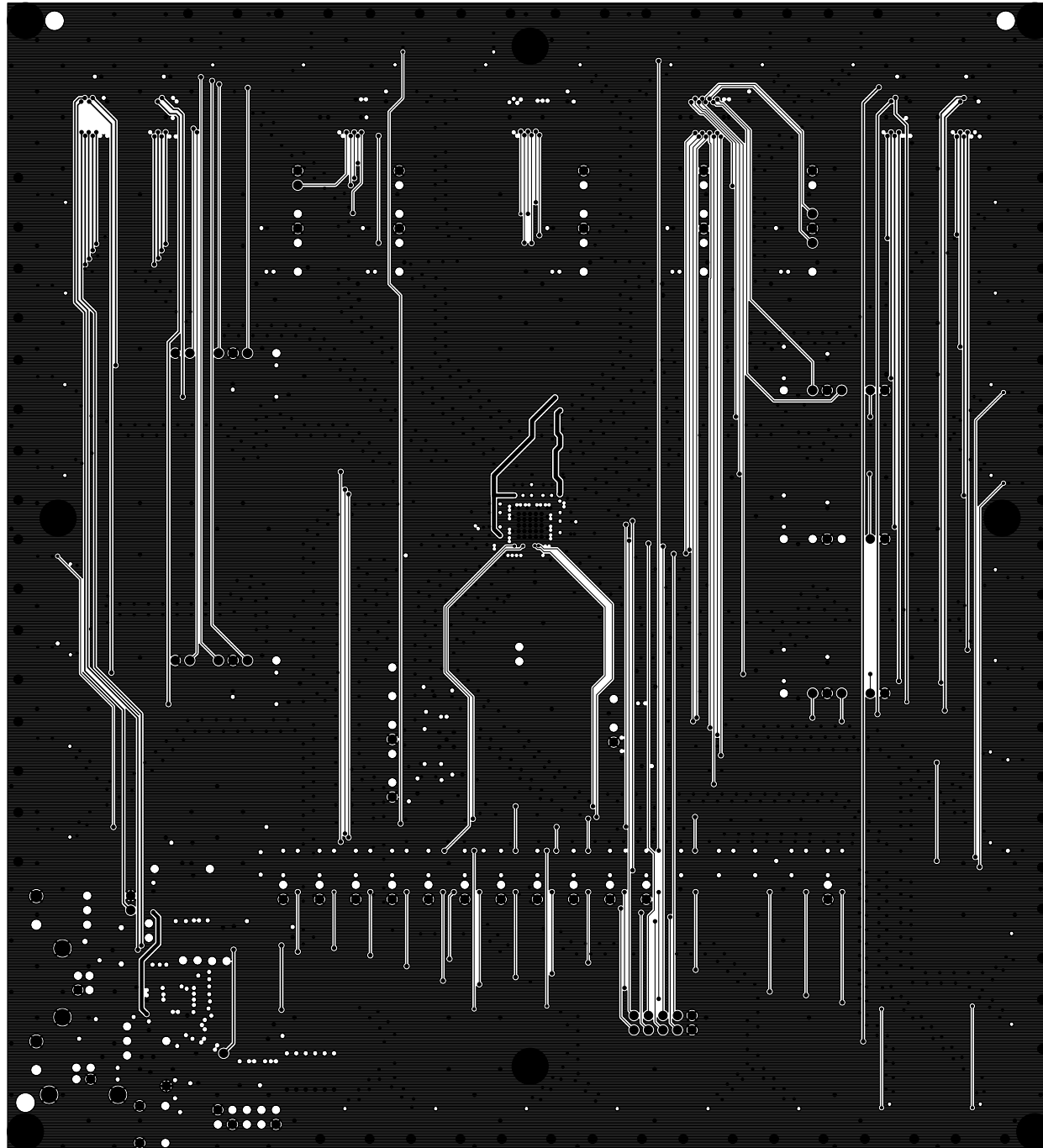
LAYER 02

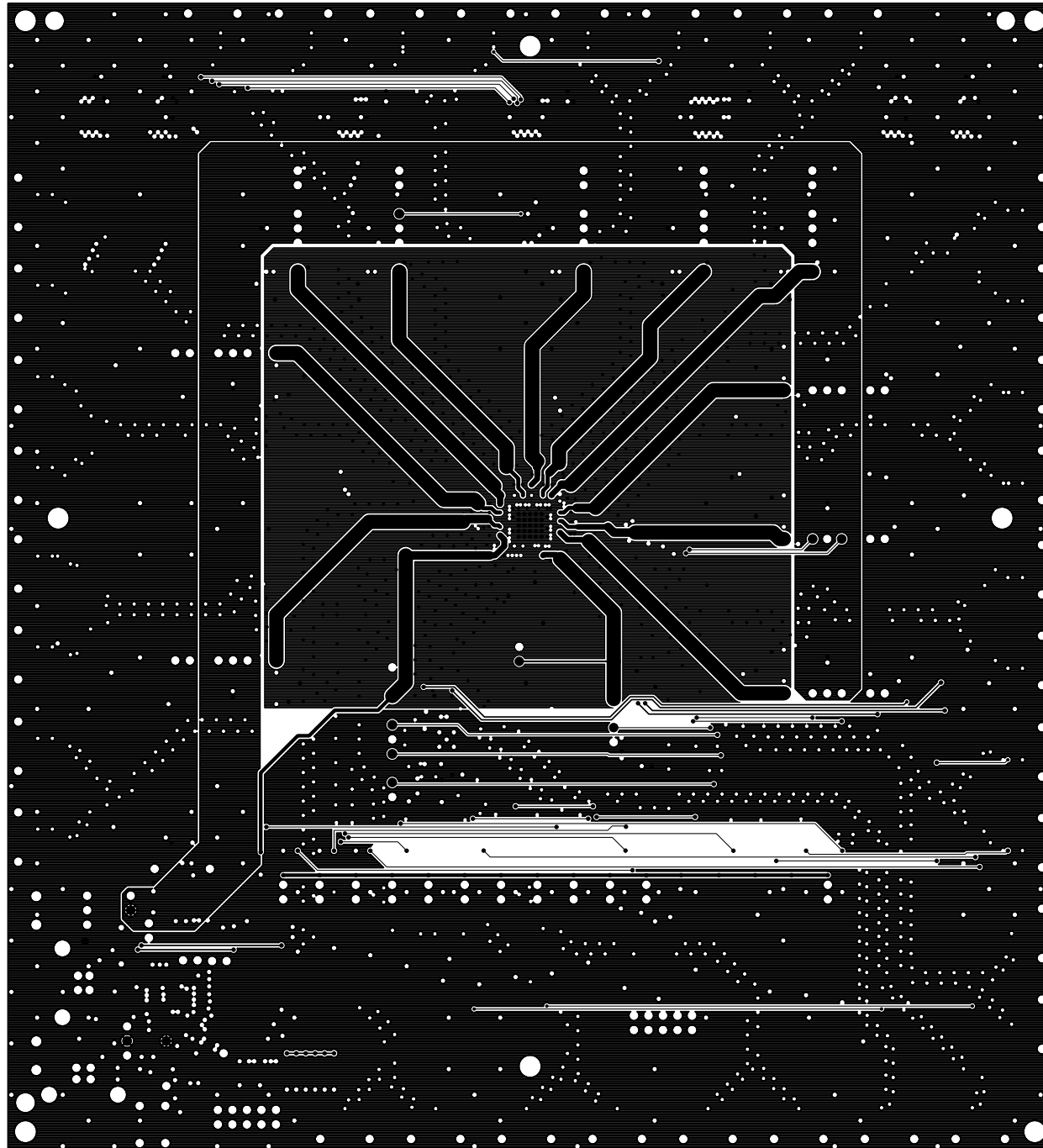


LAYER 03

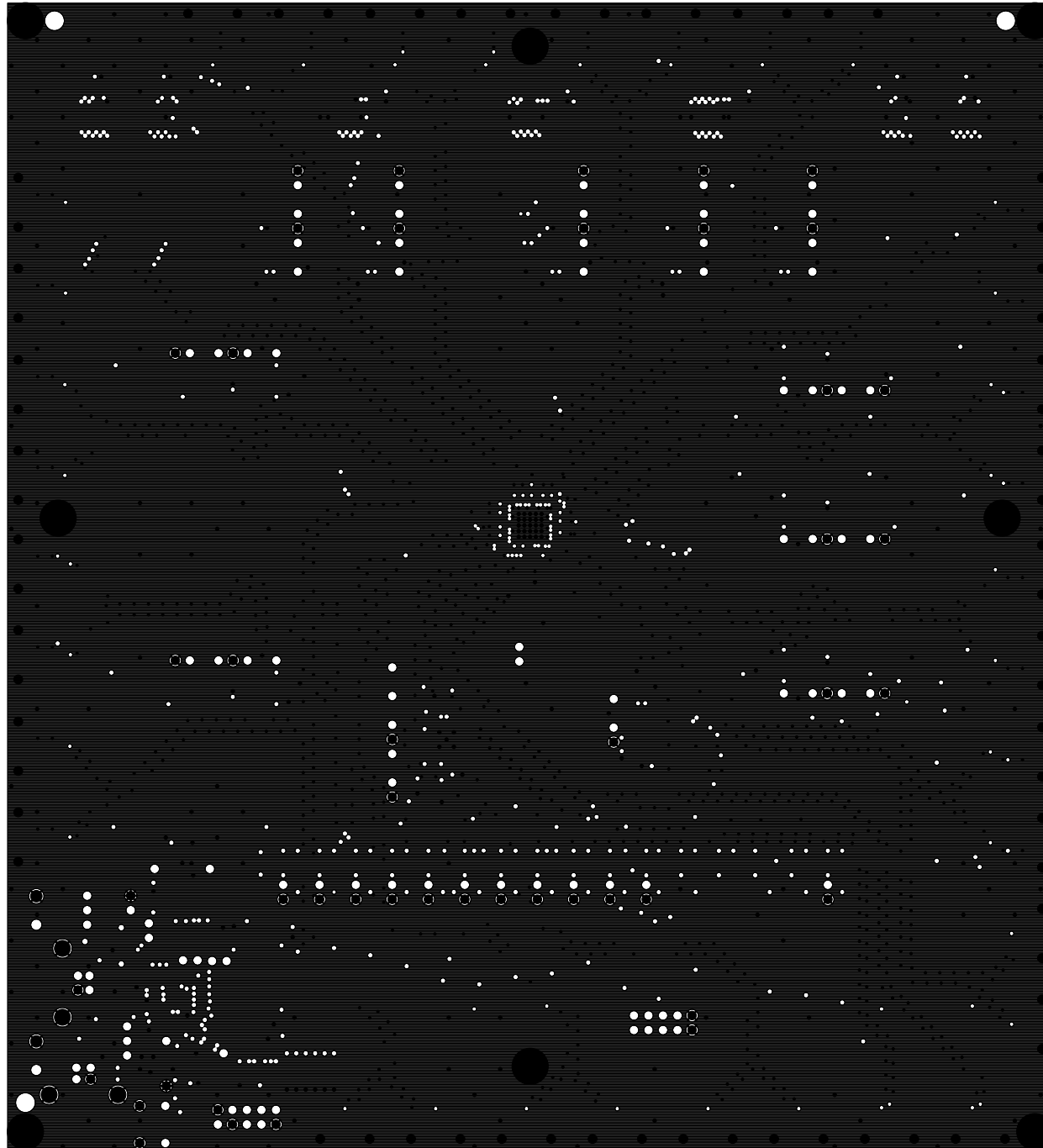


LAYER 04

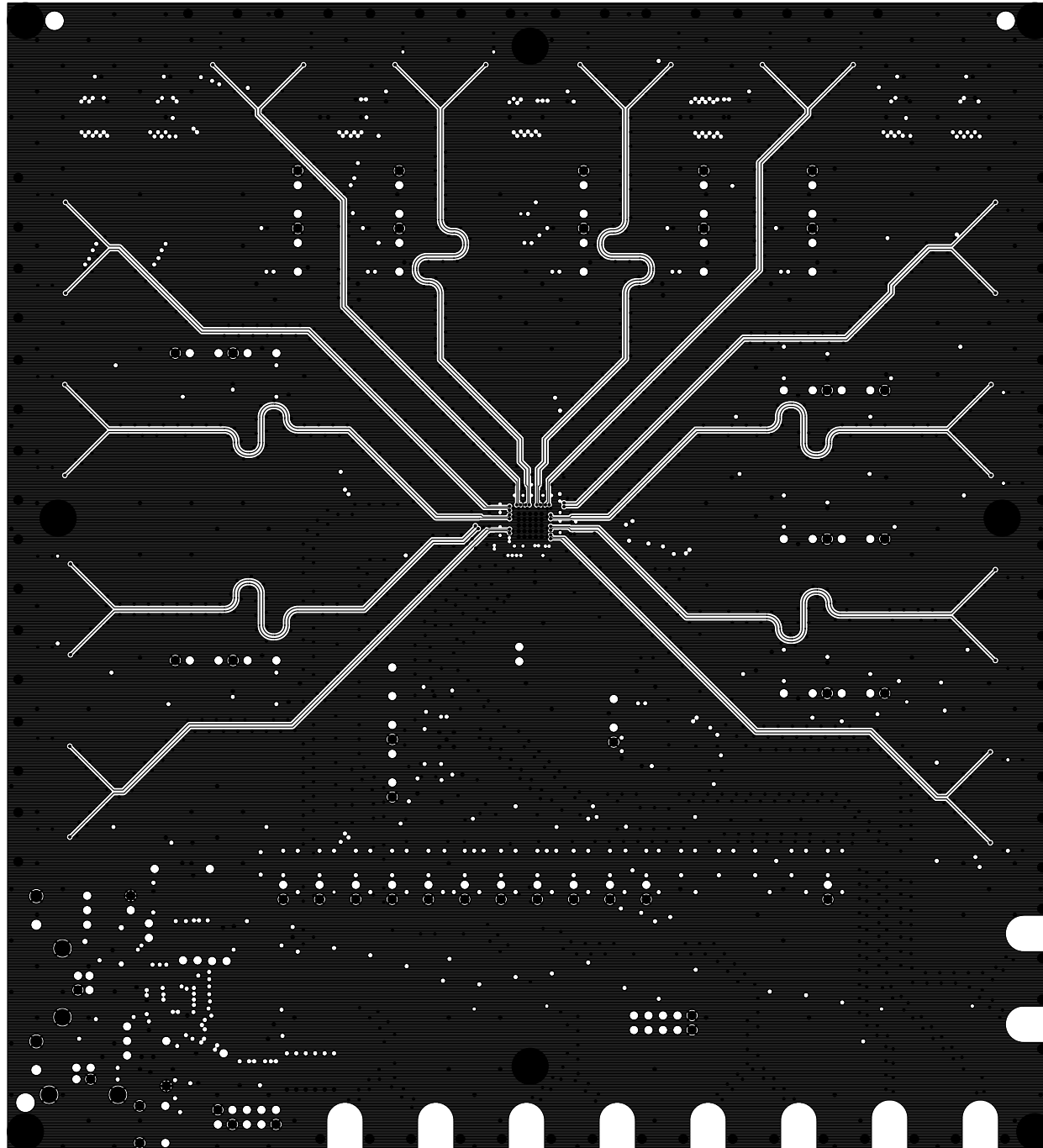




LAYER 06



LAYER 07

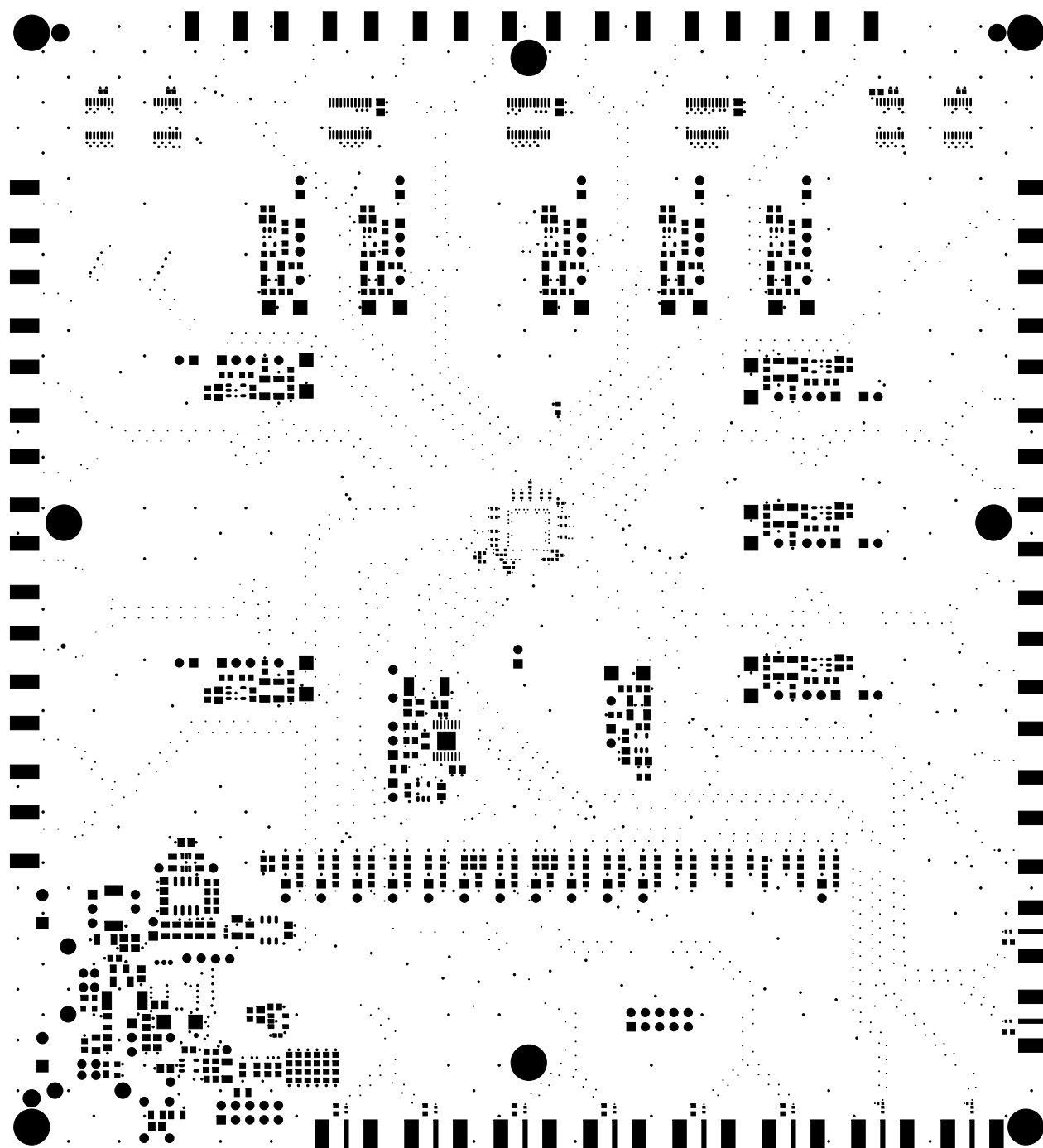


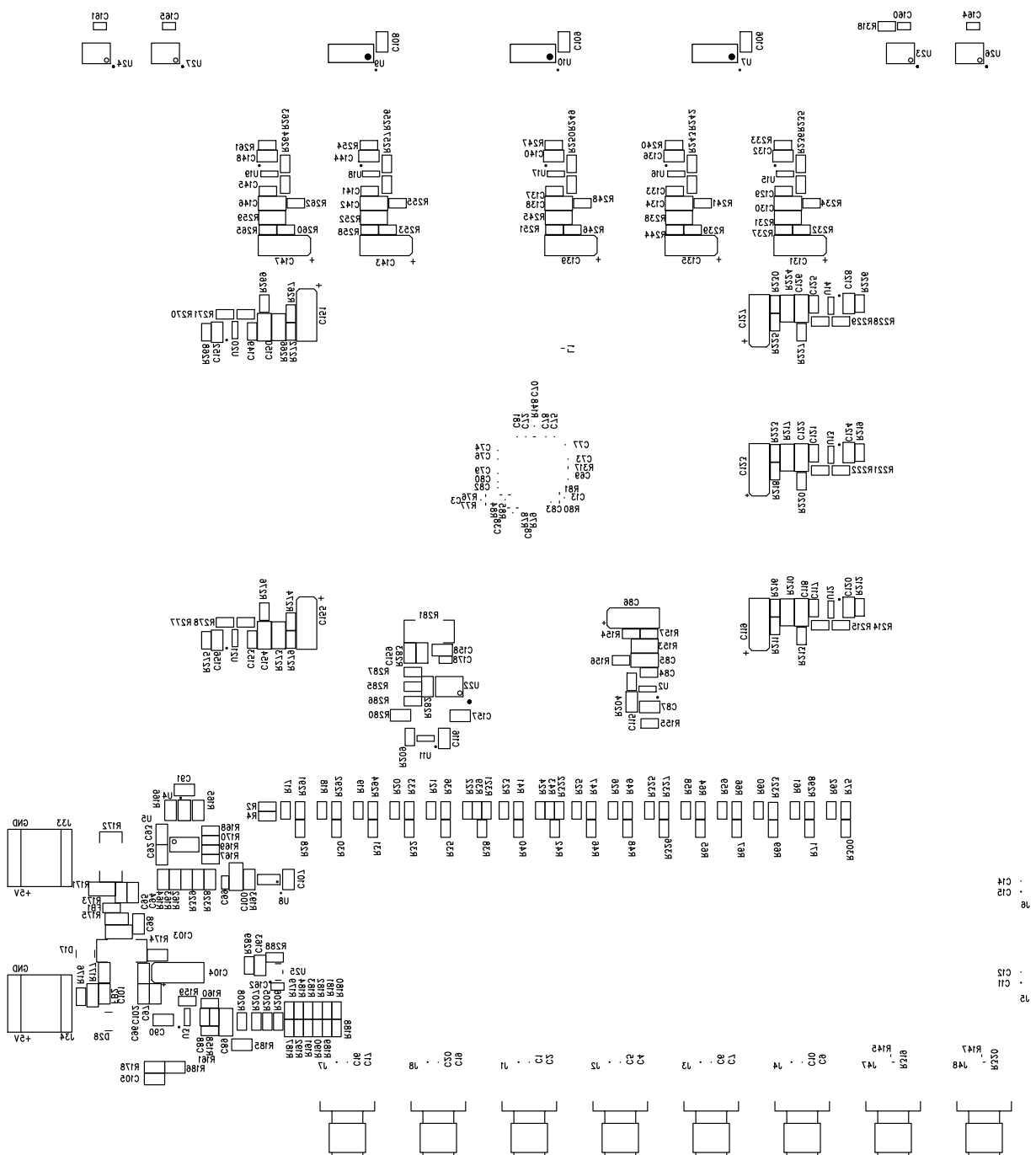
SECONDARY SIDE





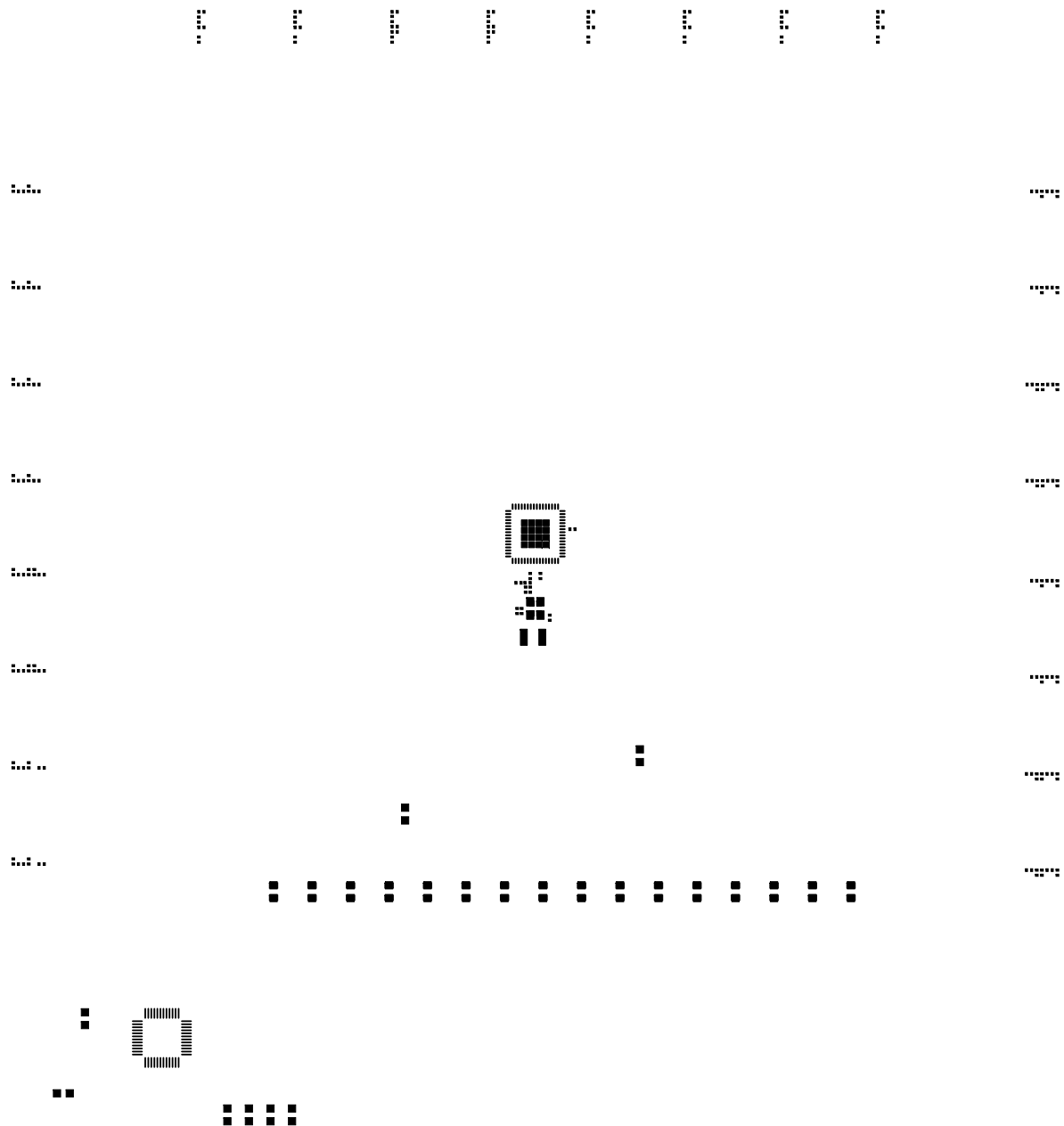
SECONDARY SOLDER MASK





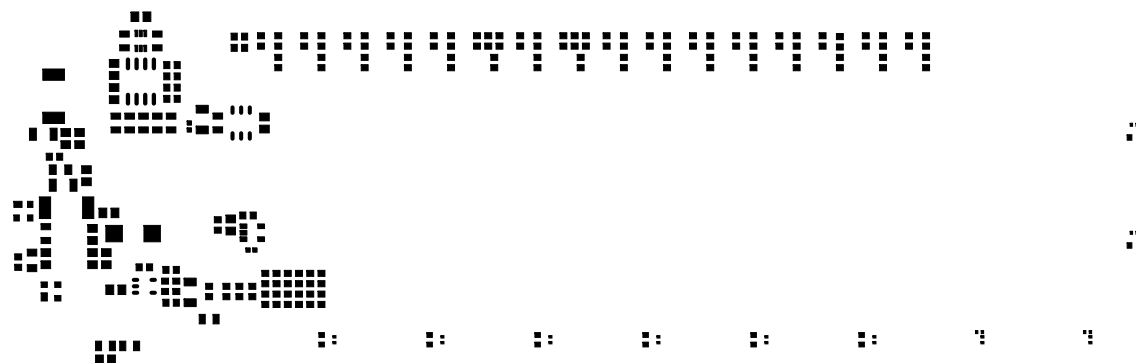
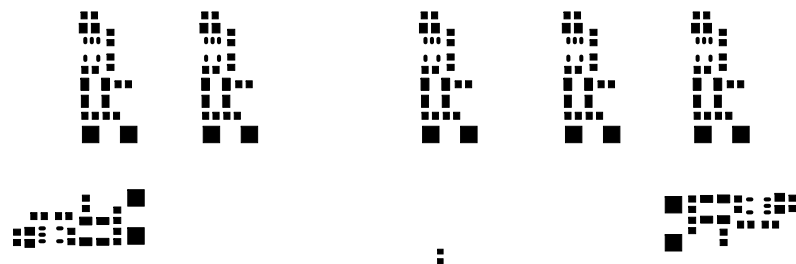
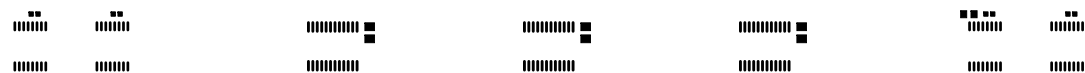


PRIMARY SOLDER PASTE

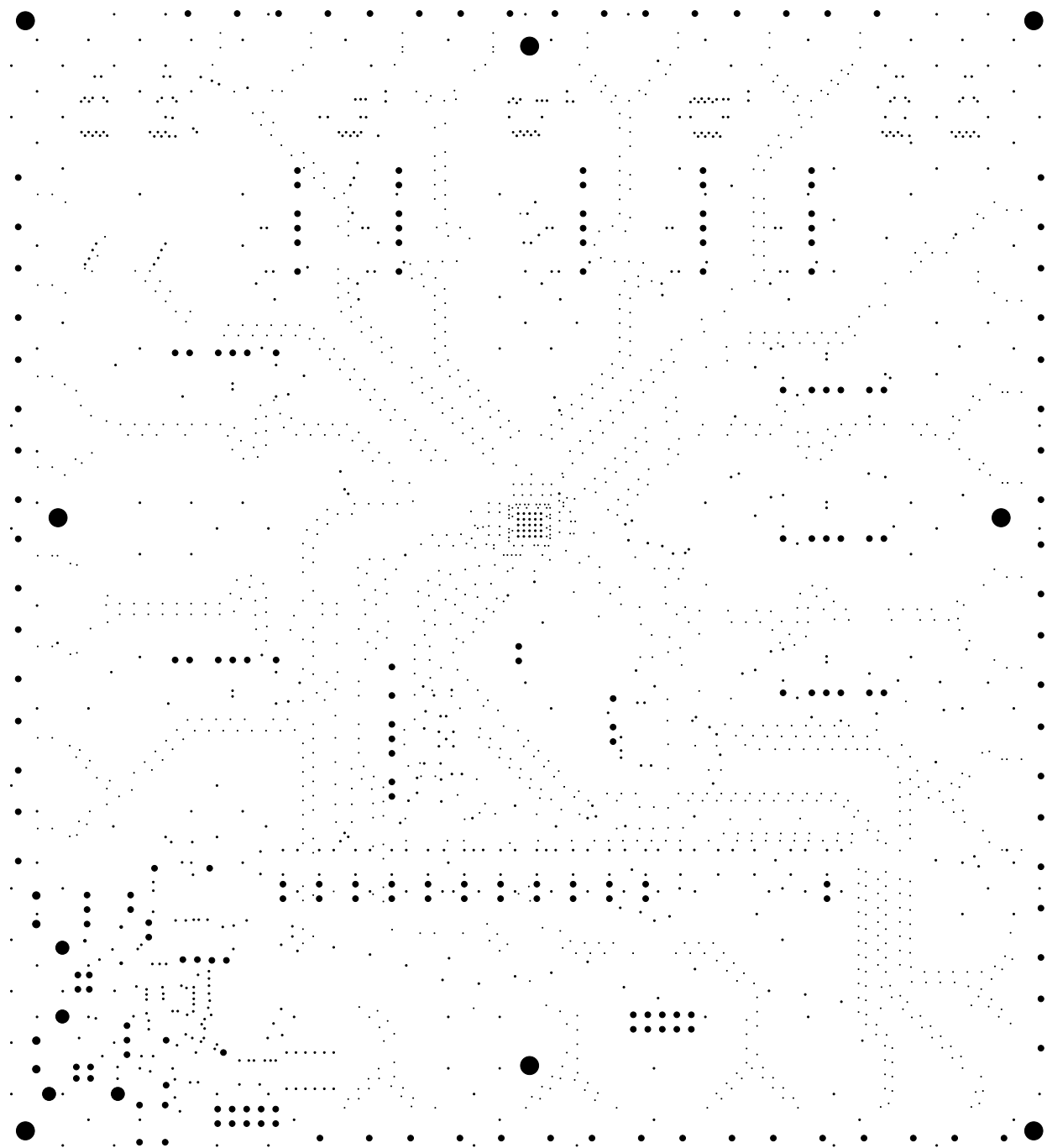




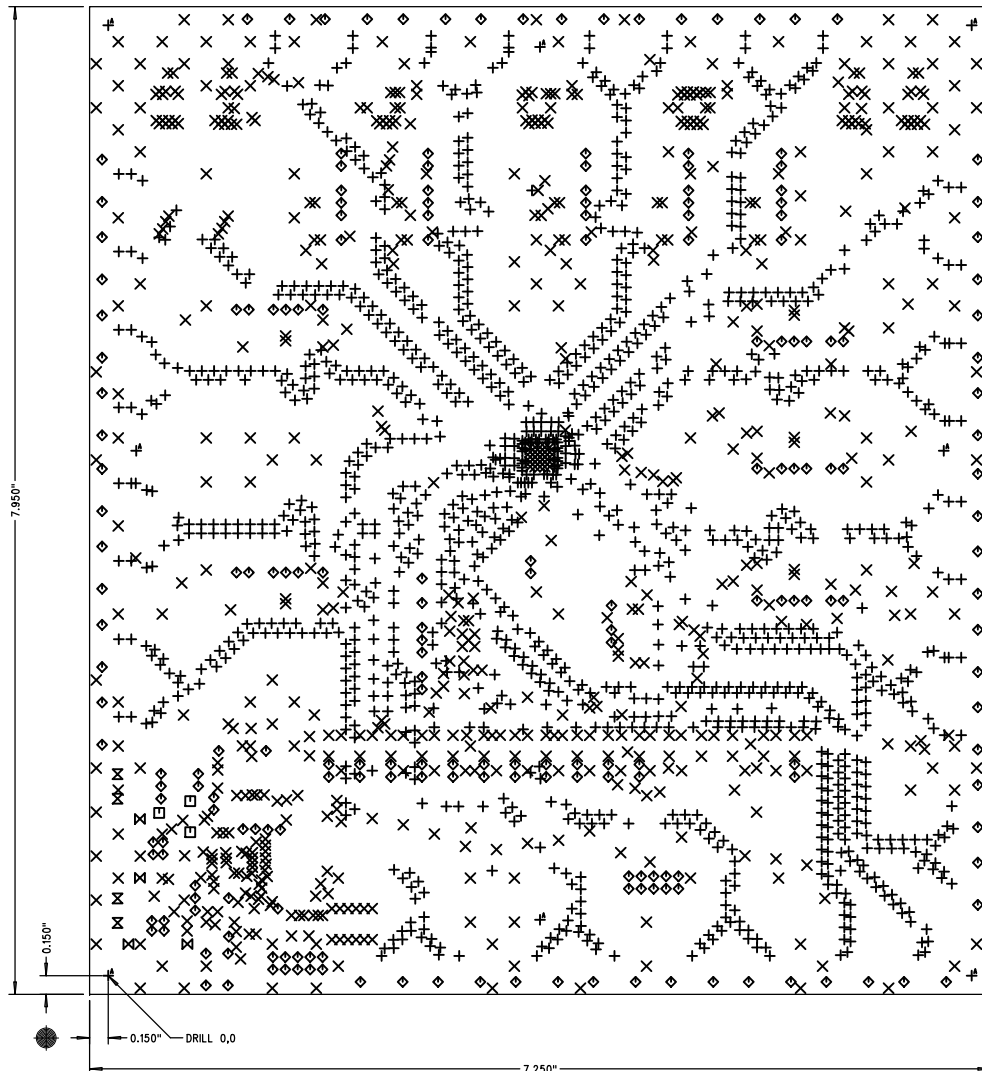
SECONDARY SOLDER PASTE







PRIMARY DRILL



NOTES : UNLESS OTHERWISE SPECIFIED

1. MANUFACTURE IN ACCORDANCE WITH IPC-6012, TYPE 3, CLASS 2.
2. END PRODUCT FEATURES SHALL NOT VARY MORE THAN 20% FROM ARTWORK ORIGINALS.
3. LAMINATE AND PREPREG SHALL BE AS PER IPC-4101/26,83,98 WITH A DECOMPOSITION TEMPERATURE $\geq 345^{\circ}\text{C}$, COLOR, NATURAL.
4. COPPER WEIGHT SHALL BE 0.5 OZ./SQ. FT. BEFORE PLATING.
5. ALL PLATED THROUGH HOLES SHALL HAVE A MINIMUM OF 0.001" COPPER.
6. DRILL HOLE TOLERANCE AFTER PLATING SHALL BE ± 0.003 ".
7. MINIMUM ANNUAL RING SHALL BE 0.001".
8. MINIMUM ANNUAL RING AT EMERGENT CONDUCTORS SHALL BE 0.003".
9. FINAL PCB THICKNESS SHALL BE 0.062" $\pm 10\%$.
10. WARP/TWIST SHALL NOT EXCEED 1.0%.
11. FINISH SHALL BE LPI, BLUE SMOBC, ENIG BOTH SIDES.
12. SILKSCREEN WITH NONCONDUCTIVE WHITE EPOXY INK.
13. INTERNAL 0.175MM TRACES TO BE 50 OHM $Z_0 \pm 5\%$.
- EXTERNAL 0.275MM TRACES TO BE 50 OHM $Z_0 \pm 5\%$.
- TOP 0.762MM TRACES TO BE 50 OHM $Z_0 \pm 5\%$ REF TO L03.
- BOTTOM 0.762MM TRACES TO BE 50 OHM $Z_0 \pm 5\%$ REF TO L06.
14. VENDOR TO PROVIDE PCB MICRO-SECTION OF COUPON AREA & TDR TEST REPORT.
15. REFERENCE ADDITIONAL FAB NOTES IN FILE README.TXT


LAYER STACKUP

FILE NAMES

PRIMARY SILKSCREEN	538x-4x-64PIN-X0_PSS.PHO
PRIMARY SOLDERMASK	538x-4x-64PIN-X0_PSM.PHO
PRIMARY SIDE	538x-4x-64PIN-X0_PRI.PHO
370HR - 7MIL THK	
RF ROUTE/GND	538x-4x-64PIN-X0_L02.PHO
370HR - 7MIL THK	
GROUND PLANE	538x-4x-64PIN-X0_L03.PHO
FR-4 IPC-4101/26,83,98	
DIGITAL ROUTE/GND	538x-4x-64PIN-X0_L04.PHO
FR-4 IPC-4101/26,83,98	
VDD0x, VDD0UT, GND	538x-4x-64PIN-X0_L05.PHO
FR-4 IPC-4101/26,83,98	
GROUND PLANE	538x-4x-64PIN-X0_L06.PHO
370HR - 7MIL THK	
RF ROUTE/GND	538x-4x-64PIN-X0_L07.PHO
370HR - 7MIL THK	
SECONDARY SIDE	538x-4x-64PIN-X0_SEC.PHO
SECONDARY SOLDERMASK	538x-4x-64PIN-X0_SSM.PHO
SECONDARY SILKSCREEN	538x-4x-64PIN-X0_SSS.PHO

SCALE: NONE

SIZE	QTY	SYM	PLT	TOOL	TOL
0.006	1354	+	P	1	+0/-0.006
0.012	701	×	P	2	+0/-0.012
0.020	3	□	P	3	+/-0.003
0.040	215	◇	P	4	+/-0.003
0.052	4	⊗	P	5	+/-0.003
0.091	4	⊗	P	6	+/-0.003
0.125	8	A	P	7	+/-0.003

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DIMENSIONS ARE IN INCHES AND APPLY AFTER FINISH DIMENSIONS IN BRACKETS () ARE IN MILLIMETERS INTERPRET DRAWING PER MIL-D-1000		TOLERANCES		NAME: S1538x_4x_64Pin_Layout_X0	
HOLE TOLERANCES PER 78027		DESIGN		SIZE	
DECIMALS	ANGLES	TM		05DEC2017	
.XX +/-	+/-	LAYOUT		AA	
.XXX +/-	+/-	PART TO BE FREE OF BURRS		10DEC2017	
SURFACES		BEND RADIUS		BEND RELIEF	
MICRONS		MAX		MAX	
MICRONS		MAX		MAX	
DO NOT SCALE DRAWING		SCALE 1:1		FABRICATION DRAWING	
SHEET 1 OF 1					